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General Purpose Transistors

PNP Silicon

BC856ALT1G Series

Features

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage BC856, SBC856 BC857, SBC857 BC858, NSVBC858, BC859	V _{CEO}	-65 -45 -30	V
Collector-Base Voltage BC856, SBC856 BC857, SBC857 BC858, NSVBC858, BC859	V _{CBO}	-80 -50 -30	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current – Continuous	Ι _C	-100	mAdc
Collector Current – Peak	Ι _C	-200	mAdc

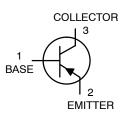
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

2. Alumina = 0.4 x 0.3 x 0.024 in 99.5% alumina.







MARKING DIAGRAM



xx = Device Code

xx = (Refer to page 6)

(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

M = Date Code*

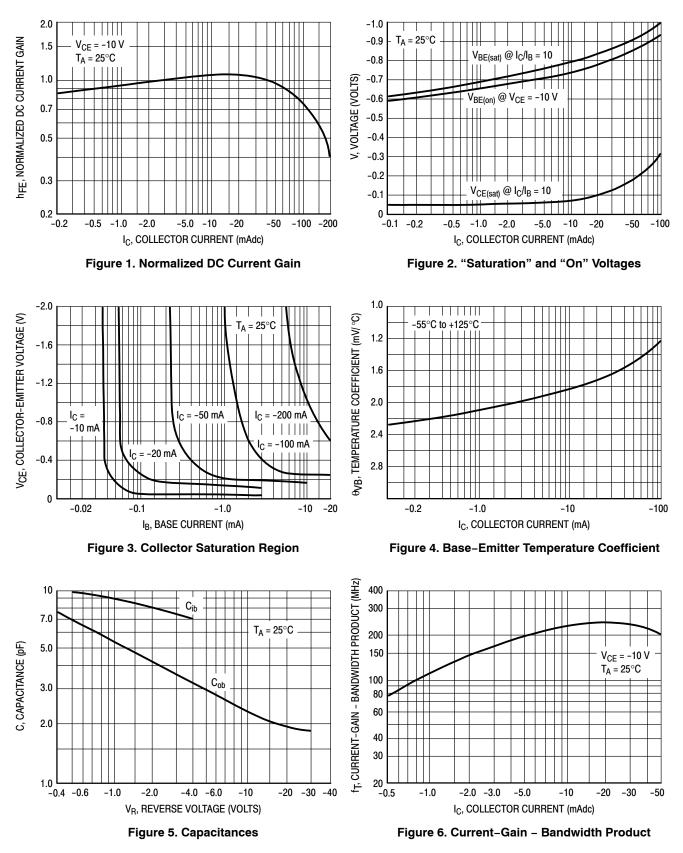
⁼ Pb-Free Package

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage BC856, SBC856 Series (I _C = -10 mA) BC857, SBC857 Series BC858, NSBVC858 BC859 Series	V _{(BR)CEO}	-65 -45 -30			V
,			-	-	
	V _{(BR)CES}	-80 -50 -30	_ _ _	- - -	V
Collector – Base Breakdown Voltage BC856, SBC856 Series (I _C = –10 μA) BC857, SBC857 Series BC858, NSVBC858, BC859 Series	V _{(BR)CBO}	80 50 30	- - -	- - -	V
$ \begin{array}{ll} \mbox{Emitter} - \mbox{Base Breakdown Voltage} & BC856, SBC856 Series \\ (I_E = -1.0 \ \mu A) & BC857, SBC857 Series \\ BC858, NSVBC858, BC859 Series \\ \end{array} $	V _{(BR)EBO}	-5.0 -5.0 -5.0	- - -	- - -	V
Collector Cutoff Current (V _{CB} = -30 V) (V _{CB} = -30 V, T _A = 150° C)	I _{CBO}	-		-15 -4.0	nA μA
ON CHARACTERISTICS					
$ \begin{array}{llllllllllllllllllllllllllllllllllll$	h _{FE}		90 150 270		-
$(I_{\rm C} = -2.0 \text{ mA}, V_{\rm CE} = -5.0 \text{ V})$ BC856A, SBC856A, BC857A,		125	180	250	
SBC857A, BC858A BC856B, SBC856B, BC857B, SBC857B, BC858B,		220	290	475	
NSVBC858B, BC859B BC857C, SBC857C, BC858C, BC859C		420	520	800	
Collector – Emitter Saturation Voltage ($I_C = -10 \text{ mA}, I_B = -0.5 \text{ mA}$) ($I_C = -100 \text{ mA}, I_B = -5.0 \text{ mA}$)	V _{CE(sat)}			-0.3 -0.65	V
Base – Emitter Saturation Voltage $(I_C = -10 \text{ mA}, I_B = -0.5 \text{ mA})$ $(I_C = -100 \text{ mA}, I_B = -5.0 \text{ mA})$	V _{BE(sat)}		-0.7 -0.9		V
Base – Emitter On Voltage ($I_C = -2.0 \text{ mA}, V_{CE} = -5.0 \text{ V}$) ($I_C = -10 \text{ mA}, V_{CE} = -5.0 \text{ V}$)	V _{BE(on)}	-0.6 -		-0.75 -0.82	V
SMALL-SIGNAL CHARACTERISTICS			-	-	-
Current – Gain – Bandwidth Product ($I_C = -10 \text{ mA}, V_{CE} = -5.0 \text{ Vdc}, f = 100 \text{ MHz}$)	f _T	100	_	_	MHz
Output Capacitance (V _{CB} = -10 V, f = 1.0 MHz)	C _{ob}	-	-	4.5	pF
Noise Figure (I _C = -0.2 mA, V _{CE} = -5.0 Vdc, R _S = 2.0 kΩ, f = 1.0 kHz, BW = 200 Hz) BC856, SBC856, BC857, SBC857, BC858, NSVBC858 Series	NF	_	_	10	dB
BC859 Series		-	-	4.0	
SWITCHING CHARACTERISTICS			1	•	
Delay Time (V _{CC} = -3.0 Vdc, I _C = -10 mA, I _E = -1 mA)	t _d	-	35	-	ns
Rise Time (V _{CC} = -3.0 Vdc, I _C = -10 mA, I _E = -1 mA)	t _r	-	25	-	ns
Storage Time (V _{CC} = -3.0 Vdc, I _C = -10 mA, I _E = -1 mA)	t _s	-	310	-	ns
Fall Time (V _{CC} = -3.0 Vdc, I _C = -10 mA, I _E = -1 mA)	t _f	-	40	-	ns

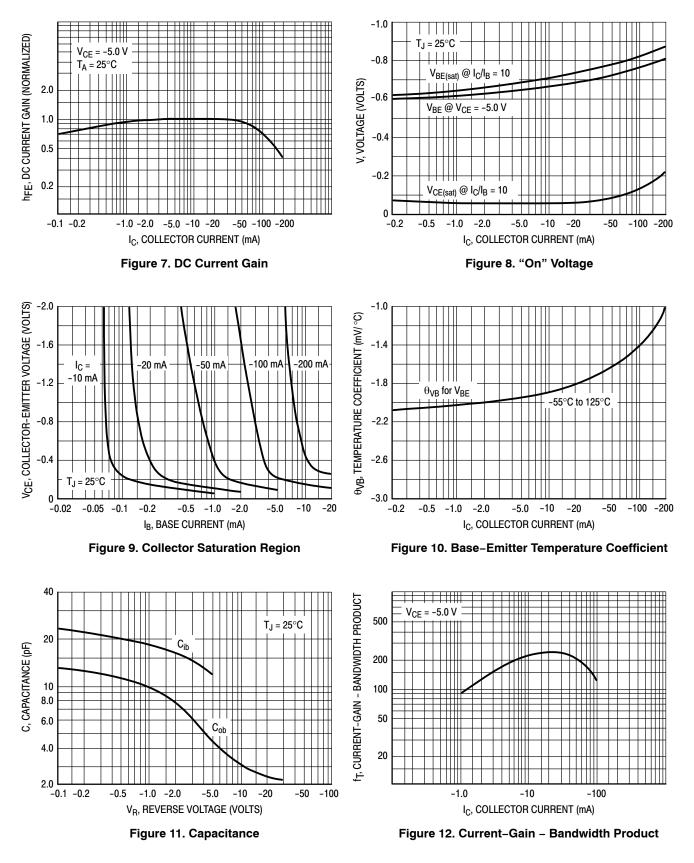
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

BC857/BC858/BC859/SBC857/NSVBC858



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BC856/SBC856



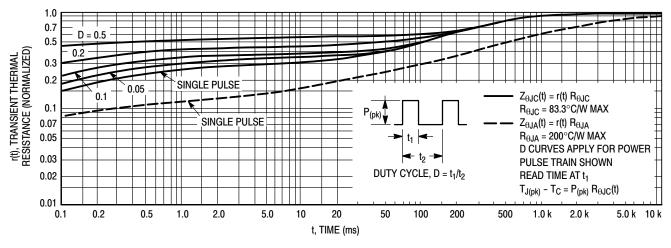


Figure 13. Thermal Response

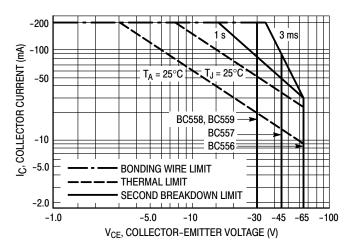


Figure 14. Active Region Safe Operating Area

The safe operating area curves indicate I_C-V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 14 is based upon $T_{J(pk)} = 150^{\circ}$ C; T_{C} or T_{A} is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ}$ C. $T_{J(pk)}$ may be calculated from the data in Figure 13. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by the secondary breakdown.

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]	
BC856ALT1G	ЗA	SOT-23	3,000 / Tape & Reel	
SBC856ALT1G*		(Pb-Free)		
BC856ALT3G			10,000 / Tape & Reel	
BC856BLT1G	3B	SOT-23	3,000 / Tape & Reel	
SBC856BLT1G*		(Pb-Free)		
BC856BLT3G			10,000 / Tape & Reel	
SBC856BLT3G*				
BC857ALT1G	3E	SOT-23	3,000 / Tape & Reel	
SBC857ALT1G*		(Pb-Free)		
BC857BLT1G	3F	SOT-23	3,000 / Tape & Reel	
SBC857BLT1G*		(Pb-Free)		
BC857BLT3G	_		10,000 / Tape & Reel	
NSVBC857BLT3G*	_			
BC857CLT1G	3G	SOT-23 (Pb-Free)	3,000 / Tape & Reel	
SBC857CLT1G*				
BC857CLT3G			10,000 / Tape & Reel	
BC858ALT1G	3J	SOT-23 (Pb-Free)	3,000 / Tape & Reel	
BC858BLT1G	ЗК	SOT-23		
NSVBC858BLT1G*		(Pb-Free)		
BC858BLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel	
BC858CLT1G	3L	SOT-23 (Pb-Free)	3,000 / Tape & Reel	
BC858CLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel	
BC859BLT1G	4B	SOT-23 (Pb-Free)	3,000 / Tape & Reel	
BC859BLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel	
BC859CLT1G	4C	SOT-23 (Pb-Free)	3,000 / Tape & Reel	
BC859CLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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TOP VIEW

SIDE VIEW

Нe

DETAIL A

-3X b

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SCALE 4:1

A____ ' A1SOT-23 (TO-236) CASE 318 ISSUE AT

0.25

-1.1

DETAIL A

END VIEW

DATE 01 MAR 2023

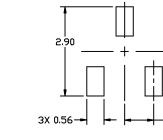
3X -0.95

0.95

NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	MILLIMETERS			INCHES		
DIM	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	
Α	0.89	1.00	1.11	0.035	0.039	0.044	
A1	0.01	0.06	0.10	0.000	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.017	0.020	
с	0.08	0.14	0.20	0.003	0.006	0.008	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
e	1.78	1.90	2.04	0.070	0.075	0.080	
L	0.30	0.43	0.55	0.012	0.017	0.022	
L1	0.35	0.54	0.69	0.014	0.021	0.027	
Η _E	2.10	2.40	2.64	0.083	0.094	0.104	
Т	0*		10*	0*		10*	



PITCH RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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